

Application Number: 10/654,167

Dkt. No.: DT-024-US-01

Listing of Claims

- 1.(Previously presented) A hot melt adhesive composition comprising:
- (a) an ethylene methyl methacrylate copolymer having a peak melting point of no greater than about  $67^{\circ}\text{C} \pm 6^{\circ}\text{C}$ ;
  - (b) a wax; and
  - (c) a tackifying resin,
- with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
- 2.(Original) The composition of claim 1 further comprising an oil.
- 3.(Cancelled)
- 4.(Previously presented) The composition of claim 1 further comprising an antioxidant.
- 5.(Previously presented) The composition of claim 1 further comprising a copolymer.
- 6.(Previously presented) The composition of claim 1 further comprising a block copolymer.
- 7-8.(Cancelled)
- 9.(Original) A package formulation comprising:
- (a) the composition of claim 1; and
  - (b) instructions for application of the composition to a substrate.
- 10.(canceled)

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11.(Previously presented) A hot melt adhesive composition consisting essentially of:

- (a) an autoclave reactor ethylene methyl methacrylate copolymer;
- (b) a wax; and
- (c) a tackifying resin.

12.(Original) The composition of claim 11 further consisting essentially of an oil.

13.(Cancelled)

14.(Previously presented) The composition of claim 11 further consisting essentially of an antioxidant.

15-16.(canceled)

17.(Original) The composition of claim 11 further consisting essentially of a block copolymer.

18.(canceled)

19.(Withdrawn) A method of using a hot melt adhesive composition comprising:

- (a) providing a hot melt adhesive composition comprising:
  - (i) an ethylene methyl methacrylate copolymer having a peak melting point of no greater than about  $67^{\circ}\text{C} \pm 6^{\circ}\text{C}$ ; and
  - (ii) a tackifying resin,with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate; and
- (b) applying the composition to a substrate.

20.(Withdrawn) The method of claim 19 wherein the method is a method of using the hot melt adhesive for book binding.

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21-25. (Canceled)